#### SN54164, SN54LS164, SN74164, SN74LS164 8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

MARCH 1974 - REVISED MARCH 1988

- Gated Serial Inputs
- Fully Buffered Clock and Serial Inputs

TYPICAL     TYPICAL       TYPE     MAXIMUM     POWER DISSIPATION       CLOCK FREQUENCY     10 mW per bit       '164     36 MHz     10 mW per bit	<ul> <li>Asy</li> </ul>	nchronous Clear	
	ТҮРЕ	MAXIMUM	
'LS164 36 MHz 10 mW per bit	<b>'164</b>	36 MHz	21 mW per bit
	′LS164	36 MHz	10 mW per bit

#### description

These 8-bit shift registers feature gated serial inputs and an asynchronous clear. The gated serial inputs (A and B) permit complete control over incoming data as a low at either input inhibits entry of the new data and resets the first flip-flop to the low level at the next clock pulse. A high-level input enables the other input which will then determine the state of the first flip-flop. Data at the serial inputs may be changed while the clock is high or low, but only information meeting the setup-time requirements will be entered. Clocking occurs on the lowto-high-level transition of the clock input. All inputs are diode-clamped to minimize transmission-line effects.

The SN54164 and SN54LS164 are characterized for operation over the full military temperature range of  $-55^{\circ}$ C to 125 °C. The SN74164 and SN74LS164 are characterized for operation from 0 °C to 70 °C.

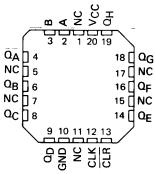
	FUNCTION TABLE												
INPUTS					OUTPL	ITS							
CLEAR	CLOCK	Α	в	٥A	Δ <sub>B</sub> Δ <sub>H</sub>								
L	х	х	х	L	L	L							
н	L	X	х	Q <sub>A0</sub>	Q <sub>B0</sub>	Q <sub>H0</sub>							
н	1	н	н	н	Q <sub>An</sub>	Q <sub>Gn</sub>							
н	1	L	X	L	Q <sub>An</sub>	Q <sub>Gn</sub>							
н	↑	×	L	L	Q <sub>An</sub>	Q <sub>Gn</sub>							

schematics of inputs and outputs

SN54164, SN54LS164 J OR W PACKAGE
SN74164 N PACKAGE
SN74LS164 D OR N PACKAGE
(TOP VIEW)

АC	1	
вС	2	13 <b>∐ Q</b> H
٥ <sub>A</sub> C	3	¹2₽ <b>0</b> G
QBC	4	11 0F
a <sub>c</sub> 🗆	5	10 🛛 QE
α <sub>D</sub> [	6	
GND [	7	8DCLK

SN54LS164 . . . FK PACKAGE (TOP VIEW)



NC – No internal connection

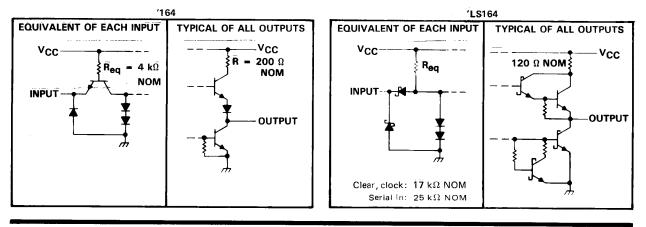
H = high level (steady state), L = low level (steady state)

X = irrelevant (any input, including transitions)

 $\uparrow$  = transition from low to high level.

 $Q_{A0}, Q_{B0}, Q_{H0} =$  the level of  $Q_A, Q_B$ , or  $Q_H$ , respectively, before the indicated steady-state input conditions were established.

 $Q_{An}, Q_{Gn}$  = the level of  $Q_A$  or  $Q_G$  before the most-recent  $\uparrow$  transition of the clock; indicates a one-bit shift.

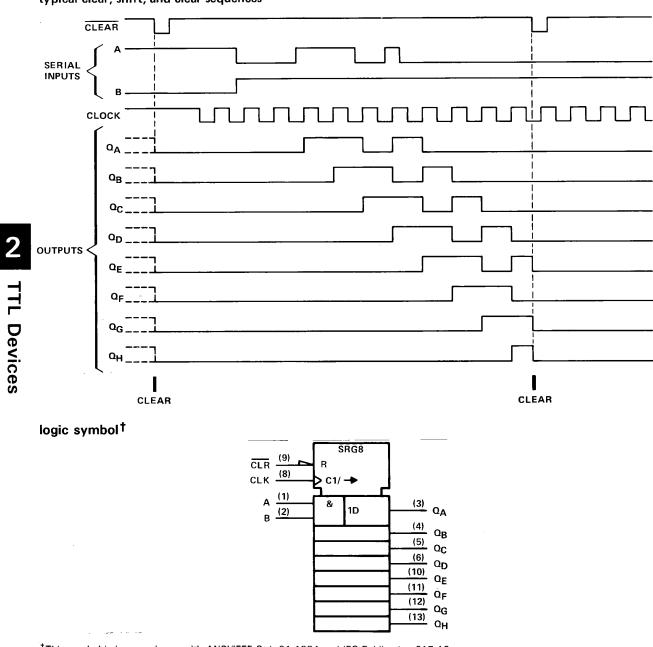




# TTL Devices

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#### SN54164, SN54LS164, SN74164, SN74LS164 8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS



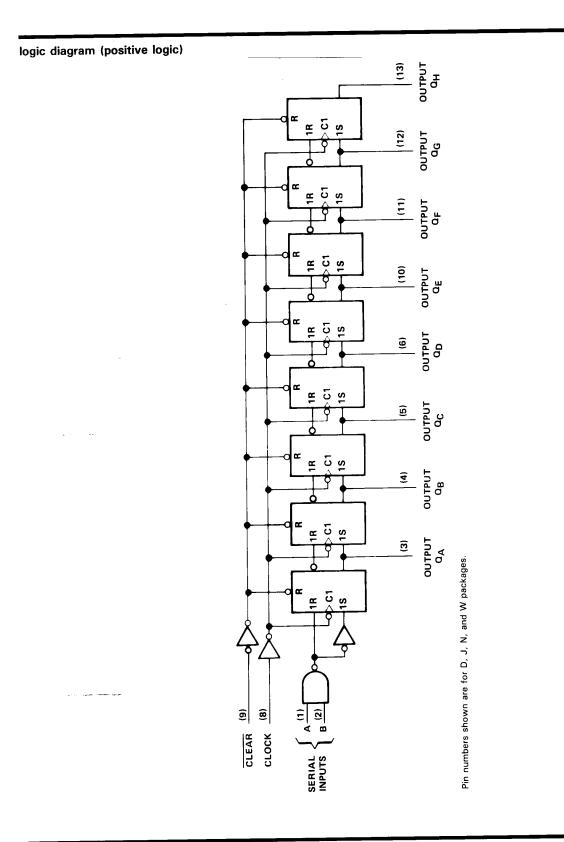
i.

typical clear, shift, and clear sequences

 $^{\dagger} This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.$ 



#### SN54164, SN54LS164, SN74164, SN74LS164 8-BIT PARALLEL OUT SERIAL SHIFT REGISTERS



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**TTL Devices** 

#### SN54164, SN74164 **8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS**

### absolute maximum ratings over oprating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)		
Operating free-air temperature range:	SN54164	–55°C to 125°C
	SN74164	

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

		SN54164 SN74164					
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			- 400			- 400	μA
Low-level output current, IQL			8			8	mA
Clock frequency, f <sub>clock</sub>	0		25	0		25	MHz
Width of clock or clear input pulse, tw	20			20			ns
Data setup time, t <sub>su</sub> (see Figure 1)	15			15			ns
Data setup time, t <sub>su</sub> (Clear Inactive) (see Figure 1)	20			20			ns
Data hold time, th (see Figure 1)	5			5			ns
Operating free-air temperature, TA	- 55		125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	_		SN54164				4	UNIT	
PARAMETER	TEST CO	TEST CONDITIONS <sup>†</sup>		түр‡	MAX	MIN	түр‡	мах	
VIH High-level input voltage			2			2			V
VIL Low-level input voltage					0.8			0.8	V
VIK Input clamp voltage	V <sub>CC</sub> = MIN,	l <sub>l</sub> = -12 mA			-1.5			-1.5	V
VOH High-level output voltage	V <sub>CC</sub> = MIN, V <sub>1L</sub> = 0.8 V,	V <sub>IH</sub> = 2 V, <sup>I</sup> OH =400 μA	2.4	3.2		2.4	3.2		V
VOL Low-level output voltage	V <sub>CC</sub> = MIN, V <sub>1L</sub> = 0.8 V,			0.2	0.4		0.2	0.4	v
I Input current at maximum input voltage	V <sub>CC</sub> = MAX,	Vi = 5.5 V,			1			1	mA
IH High-level input current	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 2.4 V			40			40	μÀ
IL Low-level input current	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 0.4 V			-1.6			-1.6	mA
IOS Short-circuit output current §	V <sub>CC</sub> = MAX		-10		-27.5	-9	-	-27.5	mΑ
		$V_{I(clock)} = 0.4 V$		30			30		mA
ICC Supply current	See Note 2	$V_{I(clock)} = 2.4 V$		37	54		37	54	

<sup>†</sup> For conditions shown at MIN or MAX, use the appropriate value specified under recommended operating conditions.

<sup>‡</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> =  $25^{\circ}$ C.

§ Not more than two outputs should be shorted at a time.

NOTE 2: ICC is measured with outputs open, serial inputs grounded, and a momentary ground, then 4.5 V, applied to clear.

#### switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER		TEST CONDI	MIN	ТҮР	MAX	UNIT	
fmax	Maximum clock frequency		C <sub>L</sub> = 15 pF	25	36		MHz
	Propagation delay time, high-to-low-level		C <sub>L</sub> = 15 pF		24	36	ns
<sup>t</sup> PHL	Q outputs from clear input	<b>B BBB C</b>	C <sub>L</sub> = 50 pF		28	42	1.3
	Propagation delay time, low-to-high-level	R <sub>L</sub> = 800 Ω,	C <sub>L</sub> = 15 pF	8	17	27	ns
₽LH	Q outputs from clock input	See Figure 1	Cլ = 50 pF	10	20	30	] '''
	Propagation delay time, high-to-low-level		C <sub>L</sub> = 15 pF	10	21	32	ns
tPHL			C <sub>L</sub> = 50 pF	10	25	37	



#### SN54LS164, SN74LS164 8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V <sub>CC</sub> (see Note 1)	
Input voltage	
Operating free-air temperature range: SN54LS164	-55°C to 125°C
SN74LS164	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

		S	SN54LS164		SN74LS164			LINIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
юн	High-level output current			- 0.4			- 0.4	mA
IOL	Low-level output current			4			8	mA
fclock	Clock frequency	0		25	0		25	MHz
tw	Width of clock or clear input pulse	20			20			ns
t <sub>su</sub>	Data setup time (See Figure 1)	15			15			ns
t <sub>su</sub>	Clear inactive setup time (See Figure 1)	20			20			ns
th	Data hold time (See Figure 1)	5			5			ns
TA	Operating free-air temperature	- 55		125	0		70	°C

# 2

**TTL Devices** 

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

CADAMETED	TEST CONDITIONS <sup>†</sup>		S	N54LS1	64	S	N74LS1	64	UNIT
PARAMETER	TEST CONDITIONS.		MIN	TYP <sup>‡</sup>	MAX	MIN	TYP <sup>‡</sup>	MAX	
VIK	$V_{CC} = MIN$ , $I_I = -18 \text{ mA}$				- 1.5			<b>-1</b> .5	V
Voн	$V_{CC} = MIN, V_{IH} = 2 V, V_{IL}$ $I_{OH} = -0.4 \text{ mA}$	= MAX,	2.5	3.5		2.7	3.5		v
	$V_{CC} = MIN,  V_{IH} = 2 V,$	$I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	v
VOL	VIL = MAX	I <sub>OL</sub> = 8 mA					0.35	0.5	v
lı l	$V_{CC} = MAX, V_I = 7 V$				0.1			0.1	mA
лн	$V_{CC} = MAX, V_I = 2.7 V$			20			20		μA
μL	$V_{CC} = MAX,  V_I = 0.4 V$				-0.4			-0.4	mA
los	V <sub>CC</sub> = MAX		- 20		- 100	- 20		- 100	mA
lcc	V <sub>CC</sub> = MAX, See Note 3			16	27		16	27	mA

<sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. <sup>‡</sup>All typical values are at  $V_{CC} = 5 V$ ,  $T_A = 25 °C$ .

<sup>§</sup>Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

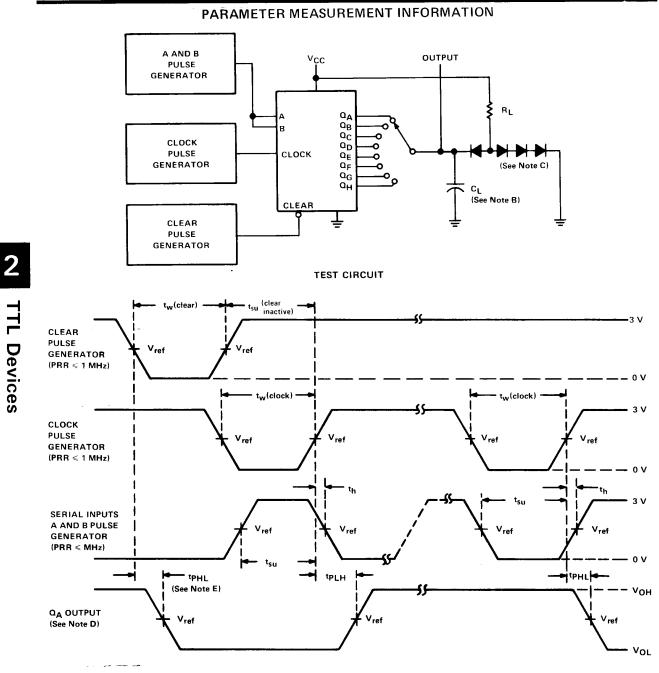
NOTE 3: I<sub>CC</sub> is measured with outputs open, serial inputs grounded, the clock input at 2.4 V, and a momentary ground, then 4.5 V applied to clear.

#### switching characteristics, $V_{CC} = 5 V$ , $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	MIN	түр	MAX	UNIT
fmax	Maximum clock frequency		25	36		MHz
<sup>t</sup> PHL	Propagation delay time, high-to-low-level Q outputs from clear input	$R_{L} = 2 k\Omega$ , $C_{L} = 15 pF$ ,		24	36	ns
<sup>t</sup> PLH	Propagation delay time, low-to-high-level Q outputs from clock input	See Figure 1		17	27	ns
tPH∟	Propagation delay time, high-to-low-level Q outputs from clock input			21	32	ns



#### SN54164, SN54LS164, SN74164, SN74LS164 **8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS**



#### VOLTAGE WAVEFORMS

- NOTES: A. The pulse generators have the following characteristics: duty cycle  $\leq$  50%, Z<sub>out</sub>  $\approx$  50  $\Omega$ ; for '164, t<sub>r</sub>  $\leq$  10 ns, t<sub>f</sub>  $\leq$  10 ns; and for 'LS164,  $t_r \le 15$  ns,  $t_f \le 6$  ns.
  - B. CL includes probe and jig capacitance.
  - C. All diodes are 1N3064 or equivalent.
  - D. QA output is illustrated. Relationship of serial input A and B data to other Q outputs is illustrated in the typical shift sequence.
  - E. Outputs are set to the high level prior to the measurement of tpHL from the clear input.
  - F. For '164,  $V_{ref}$  = 1.5 V; for 'LS164,  $V_{ref}$  = 1.3 V.

FIGURE 1-SWITCHING TIMES





#### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/30605B2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605B2A	Samples
JM38510/30605BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BCA	Samples
JM38510/30605BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BCA	Samples
JM38510/30605BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BDA	Samples
JM38510/30605BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BDA	Samples
JM38510/30605SCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SCA	Samples
JM38510/30605SCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SCA	Samples
JM38510/30605SDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SDA	Samples
JM38510/30605SDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SDA	Samples
M38510/30605B2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605B2A	Samples
M38510/30605B2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605B2A	Samples
M38510/30605BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BCA	Samples
M38510/30605BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BCA	Samples
M38510/30605BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BDA	Samples
M38510/30605BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BDA	Samples
M38510/30605SCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SCA	Samples



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Sample
M38510/30605SCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SCA	Samples
M38510/30605SDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SDA	Samples
M38510/30605SDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SDA	Samples
SN54LS164J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS164J	Samples
SN54LS164J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS164J	Samples
SN74LS164D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70	LS164	
SN74LS164D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70	LS164	
SN74LS164DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS164	Samples
SN74LS164DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS164	Sample
SN74LS164N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS164N	Sample
SN74LS164N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS164N	Sample
SN74LS164NE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS164N	Sample
SN74LS164NE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS164N	Sample
SN74LS164NSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS164	Sample
SN74LS164NSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS164	Sample
SN74LS164NSRE4	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS164	Sample
SN74LS164NSRE4	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS164	Sample
SNJ54LS164FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 164FK	Sample
SNJ54LS164FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 164FK	Sample
SNJ54LS164J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS164J	Sample

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LS164J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS164J	Samples
SNJ54LS164W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS164W	Samples
SNJ54LS164W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS164W	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS164, SN54LS164-SP, SN74LS164 :

- Catalog : SN74LS164, SN54LS164
- Military : SN54LS164
- Space : SN54LS164-SP

#### NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

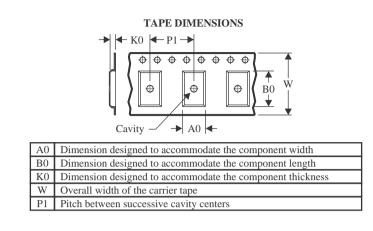
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STRUMENTS

#### TAPE AND REEL INFORMATION





#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



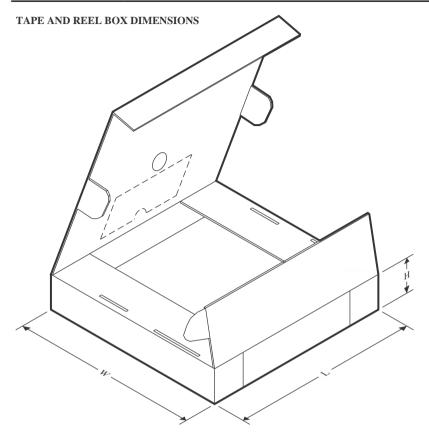
*Al	l dimensions are nominal												
	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	SN74LS164DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
	SN74LS164NSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



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# PACKAGE MATERIALS INFORMATION

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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS164DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74LS164NSR	SOP	NS	14	2000	356.0	356.0	35.0

#### TEXAS INSTRUMENTS

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#### TUBE



#### B - Alignment groove width

Device	Package Nam
*All dimensions are nominal	

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
JM38510/30605B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
JM38510/30605BDA	W	CFP	14	25	506.98	26.16	6220	NA
JM38510/30605SDA	W	CFP	14	25	506.98	26.16	6220	NA
M38510/30605B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
M38510/30605BDA	W	CFP	14	25	506.98	26.16	6220	NA
M38510/30605SDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74LS164N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS164N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS164NE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS164NE4	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54LS164FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54LS164W	W	CFP	14	25	506.98	26.16	6220	NA

# **D0014A**



# **PACKAGE OUTLINE**

#### SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



# D0014A

# **EXAMPLE BOARD LAYOUT**

#### SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# D0014A

# **EXAMPLE STENCIL DESIGN**

#### SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



#### MECHANICAL DATA

#### PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14



# FK 20

#### 8.89 x 8.89, 1.27 mm pitch

# **GENERIC PACKAGE VIEW**

#### LCCC - 2.03 mm max height

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





# **GENERIC PACKAGE VIEW**

# CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



# J0014A



# **PACKAGE OUTLINE**

#### CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
   Falls within MIL-STD-1835 and GDIP1-T14.



# J0014A

# **EXAMPLE BOARD LAYOUT**

#### CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE





## N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



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